

HVD374B

Variable Capacitance Diode for VCO

REJ03G0040-0200 Rev.2.00 Jul 01, 2005

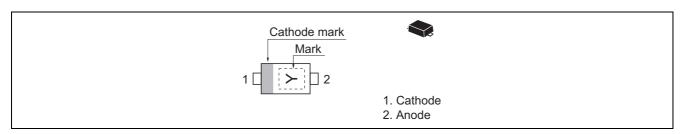
Features

- High capacitance ratio and good C-V linearity.
- To be usable at low voltage.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HVD374B	Y	SFP	PUSF0002ZB-A
			(SFP)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Reverse voltage	V_R	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

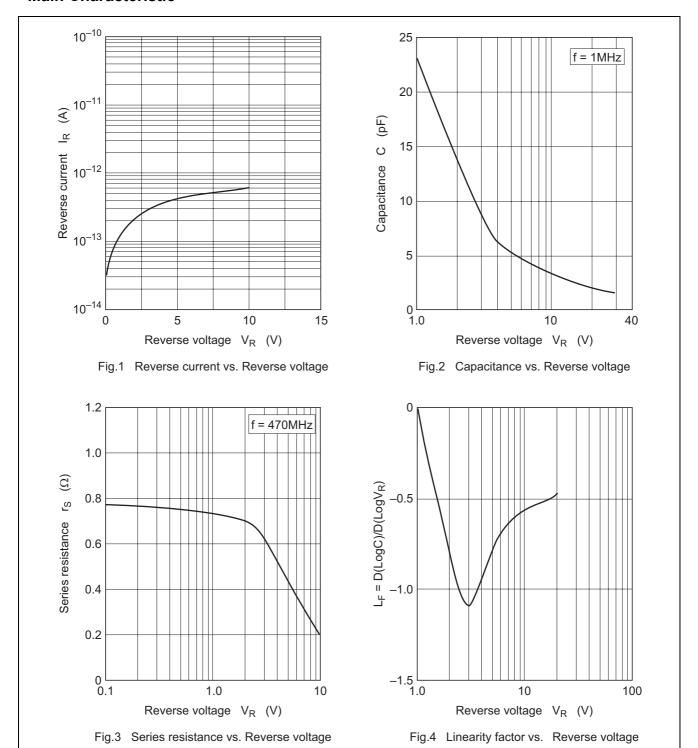
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

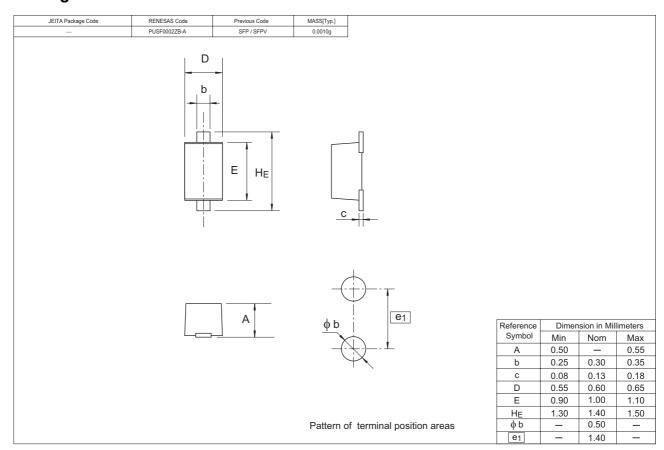
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	21.50	_	24.00	pF	V _R = 1 V, f = 1 MHz
	C ₂	12.50		14.50		V _R = 2 V, f = 1 MHz
Capacitance ratio	n	1.680	_	1.750	_	C ₁ /C ₂
Series resistance	rs	_	_	1.20	Ω	V _R = 1 V, f = 470 MHz

Note: The material of lead is exposed for cutting plane. Therefore, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions



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Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

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